# 2.5 V/3.3 V Differential LVPECL 2x2 Clock Switch and Low Skew Fanout Buffer 

## NB4L6254

## Description

The NB4L6254 is a differential 2 x 2 clock switch and drives precisely aligned clock signals through its LVPECL fanout buffers. It employs a fully differential architecture with bipolar technology, offers superior digital signal characteristics, has very low clock output skew and supports clock frequencies from DC up to 3.0 GHz .

The NB4L6254 is designed for the most demanding, skew critical differential clock distribution systems. Typical applications for the NB4L6254 are clock distribution, switching and data loopback systems of high-performance computer, networking and telecommunication systems, as well as on-board clocking of $\mathrm{OC}-3$, $\mathrm{OC}-12$ and $\mathrm{OC}-48$ communication systems. In addition, the NB4L6254 can be configured as a single 1:6 or dual 1:3 LVPECL fanout buffer.

The NB4L6254 can be operated from a single 3.3 V or 2.5 V power supply.

## Features

- Maximum Clock Input Frequency, 3 GHz
- Maximum Input Data Rate, $3 \mathrm{~Gb} / \mathrm{s}$
- Differential LVPECL Inputs and Outputs
- Low Output Skew: 50 ps Maximum Output-to-Output Skew
- Synchronous Output Enable Eliminating Output Runt Pulse Generation and Metastability
- Operating Range: Single 3.3 V or 2.5 V Supply
$\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to 3.465 V
- LVCMOS Compatible Control Inputs
- Packaged in LQFP-32
- Fully Differential Architecture
- $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ Ambient Operating Temperature
- These are $\mathrm{Pb}-$ Free Devices*
*For additional information on our $\mathrm{Pb}-$ Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Figure 1. Functional Block Diagram


[^0]NB4L6254


Figure 2. 32-Lead LQFP Pinout (Top View)

Table 1. PIN DESCRIPTION

| Pin Name | I/O | Description |
| :---: | :--- | :--- |
| CLKO, CLK0 | LVPECL Input | Differential reference clock signal input 0. |
| CLK1, CLK1 | LVPECL Input | Differential reference clock signal input 1. |
| OEAb, OEB | LVCMOS Input | Output Enable |
| SELO, SEL1 | LVCMOS Input | Clock Switch Select |
| QA[0-2], QA[0-2] <br> QB[0-2], QB[0-2] | LVPECL Output | Differential LVPECL Clock Outputs, (banks A and B) Typically terminated with $50 ~$ <br> resistor to $V_{C C}-2.0 \mathrm{~V}$. |
| GND | Power Supply | Negative Supply Voltage |
| V $C C$ | Power Supply | Positive supply voltage. All $\mathrm{V}_{\mathrm{CC}}$ pins must be connected to the positive power supply <br> for correct DC and AC operation. |

Table 2. FUNCTION TABLE

| Control | Default | $\mathbf{0}$ | $\mathbf{1}$ |
| :---: | :---: | :--- | :--- |
| OEA | 0 | QA[0-2], QA[0-2] are active. Deassertion of <br> OEA can be asynchronous to the reference <br> clock without generation of output runt pulses | QA[0-2] = L, QA[0-2] $=\mathrm{H}$ (outputs disabled). Assertion of <br> OE can be asynchronous to the reference clock without <br> generation of output runt pulses |
| $\overline{\mathrm{OEB}}$ | 0 | QB[0-2], QB[0-2] are active. Deassertion of <br> OEB can be asynchronous to the reference <br> clock without generation of output runt pulses | $\mathrm{QB}[0-2]=\mathrm{L}, \overline{\mathrm{QB}[0-2]}=\mathrm{H}$ (outputs disabled). Assertion of <br> OE can be asynchronous to the reference clock without <br> generation of output runt pulses |
| SELO, <br> SEL1 | 00 | Refer to Table 3 | Refer to Table 3 |

Table 3. CLOCK SELECT CONTROL

| SELO | SEL1 | CLK0 Routed To | CLK1 Routed to | Application Mode |
| :---: | :---: | :--- | :--- | :--- |
| 0 | 0 | QA[0:2] and QB[0:2] | - | $1: 6$ Fanout of CLK0 |
| 0 | 1 | - | QA[0:2] and QB[0:2] | $1: 6$ Fanout of CLK1 |
| 1 | 0 | QA[0:2] | QB[0:2] | Dual 1:3 Buffer |
| 1 | 1 | QB[0:2] | QA[0:2] | Dual 1:3 Buffer (Crossed) |

Table 4. ATTRIBUTES

| Characteristics | Value |
| :--- | :---: |
| Internal Input Pullup Resistor | $37.5 \mathrm{k} \Omega$ |
| Internal Input Pulldown Resistor | $75 \mathrm{k} \Omega$ |
| ESD Protection <br> Human Body Model <br> Machine Model | $>2000 \mathrm{~V}$ <br> $>200 \mathrm{~V}$ |
| Latchup Immunity | $>200 \mathrm{~mA}$ |
| Cin, inputs | 4.0 pF (TYP) |
| Moisture Sensitivity (Note 1) <br> LQFP-32 | Level 2 |
| Flammability Rating <br> Oxygen Index: 28 to 34 | $\mathrm{UL} 94 \mathrm{~V}-0$ @ 0.125 in |
| Transistor Count | 336 |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test |  |

1. For additional information, see Application Note AND8003/D.

Table 5. MAXIMUM RATINGS (Note 2)

| Symbol | Parameter | Condition | Condition | Rating | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {CC }}$ | Positive Power Supply |  |  | $-0.3 \leq \mathrm{V}_{\mathrm{CC}} \leq 3.6$ | V |
| $\mathrm{V}_{\text {IN }}$ | DC Input Voltage |  |  | $\begin{aligned} -0.3 & \leq V_{\mathrm{IN}} \leq \mathrm{V}_{\mathrm{CC}} \\ & +0.3 \end{aligned}$ | V |
| $\mathrm{V}_{\text {OUT }}$ | DC Output Voltage |  |  | $\begin{aligned} -0.3 & \leq \mathrm{V}_{\mathrm{OUT}} \leq \mathrm{V}_{\mathrm{CC}} \\ & +0.3 \end{aligned}$ | V |
| In | DC Input Current |  |  | $\pm 20$ | mA |
| $\mathrm{I}_{\text {out }}$ | LVPECL DC Output Current | Continuous Surge |  | $\begin{aligned} & \pm 50 \\ & 100 \end{aligned}$ | $\begin{aligned} & \mathrm{mA} \\ & \mathrm{~mA} \end{aligned}$ |
| $\mathrm{T}_{\text {A }}$ | Operating Temperature Range | LQFP-32 |  | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {stg }}$ | Storage Temperature Range |  |  | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |
| $\theta_{\mathrm{JA}}$ | Thermal Resistance (Junction-to-Ambient) (Note 3) | $\begin{aligned} & \hline 0 \text { lfpm } \\ & 500 \text { lfpm } \end{aligned}$ | LQFP-32 LQFP-32 | $\begin{aligned} & 80 \\ & 55 \end{aligned}$ | $\begin{aligned} & \hline{ }^{\circ} \mathrm{C} / \mathrm{W} \\ & { }^{\circ} \mathrm{C} / \mathrm{W} \end{aligned}$ |
| $\theta_{\mathrm{Jc}}$ | Thermal Resistance (Junction-to-Case) | 2S2P (Note 3) | LQFP-32 | 12 to 17 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{T}_{\text {sol }}$ | Wave Solder Pb-Free |  |  | 265 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{V}_{\mathrm{TT}}$ | Output Termination Voltage |  |  | $\mathrm{V}_{\mathrm{CC}}$ - 2.0, TYP | V |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
2. Maximum Ratings are those values beyond which device damage may occur.
3. JEDEC standard multilayer board - 2S2P (2 signal, 2 power); MIL-SPEC 883E Method 1012.1.

Table 6. DC CHARACTERISTICS $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to $3.465 \mathrm{~V}, \mathrm{GND}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$

| Symbol | Characteristic | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: |
| POWER SUPPLY CURRENT |  |  |  |  |  |
| $\mathrm{I}_{\text {GND }}$ | Power Supply Current (Outputs Open) |  | 60 | 85 | mA |

LVPECL CLOCK OUTPUTS

| $\mathrm{V}_{\mathrm{OH}}$ | LVPECL Output HIGH Voltage (Notes 4, 5) | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{CC}}=2.5 \mathrm{~V} \end{aligned}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-1145 \\ 2155 \\ 1355 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-1020 \\ 2280 \\ 1480 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-895 \\ 2405 \\ 1605 \end{gathered}$ | mV |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {OL }}$ | LVPECL Output LOW Voltage (Notes 4, 5) | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V} \\ & \mathrm{~V}_{\mathrm{CC}}=2.5 \mathrm{~V} \end{aligned}$ | $\begin{gathered} \hline \mathrm{V}_{\mathrm{CC}}-1945 \\ 1355 \\ 555 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-1770 \\ 1530 \\ 730 \end{gathered}$ | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}-1600 \\ 1700 \\ 900 \end{gathered}$ | mV |

CLOCK INPUTS

| $\mathrm{V}_{\mathrm{PP}}$ | Dynamic Differential Input Voltage (Clock Inputs) | 0.1 |  | 1.3 | V |
| :---: | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{~V}_{\mathrm{CMR}}$ | Differential Cross-point Voltage (Clock Inputs) | 1.0 |  | $\mathrm{~V}_{\mathrm{CC}}-0.3$ | V |

LVCMOS CONTROL INPUTS

| $\mathrm{V}_{\mathrm{IH}}$ | Output HIGH Voltage (LVTTL/LVCMOS) | 2.0 |  | V |
| :--- | :--- | :---: | :---: | :---: |
| $\mathrm{~V}_{\mathrm{IL}}$ | Output LOW Voltage (LVTTL/LVCMOS) |  | V |  |
| $\mathrm{I}_{\mathrm{IH}}$ | Input Current $\mathrm{V}_{\mathrm{IN}}=\mathrm{V}_{\mathrm{CC}}$ or $\mathrm{V}_{\mathrm{IN}}=\mathrm{GND}$ | -100 |  |  |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 Ifpm.
4. LVPECL Outputs loaded with $50 \Omega$ termination resistors to $\mathrm{V}_{T T}=\mathrm{V}_{\mathrm{CC}}-2.0 \mathrm{~V}$ for proper operation.
5. LVPECL Output parameters vary $1: 1$ with $\mathrm{V}_{\mathrm{CC}}$.

Table 7. AC CHARACTERISTICS $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to $3.465 \mathrm{~V}, \mathrm{GND}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ (Note 6)

\begin{tabular}{|c|c|c|c|c|c|}
\hline Symbol \& Characteristic \& Min \& Typ \& Max \& Unit <br>
\hline VINPP \& Differential Input Voltage (Peak-to-Peak) \& 0.3 \& \& 1.3 \& V <br>
\hline $\mathrm{V}_{\text {CMR }}$ \& Differential Input Cross-Point Voltage (Clock Inputs) \& 1.2 \& \& $\mathrm{V}_{\mathrm{CC}}-0.3$ \& V <br>
\hline $\mathrm{f}_{\mathrm{IN}}$ \& Clock Input Frequency \& 0 \& \& 3.0 \& GHz <br>
\hline Voutp \& Differential Output Output Voltage Amplitude (Peak-to-Peak)
(Note 7)

$f_{\mathrm{O}}<1.1 \mathrm{GHz}$
$\mathrm{f}_{\mathrm{O}}<2.5 \mathrm{GHz}$

$\mathrm{f}_{\mathrm{O}}<3.0 \mathrm{GHz}$ \& \[
$$
\begin{gathered}
0.45 \\
0.35 \\
0.2
\end{gathered}
$$

\] \& \[

$$
\begin{aligned}
& 0.70 \\
& 0.55 \\
& 0.35
\end{aligned}
$$
\] \& \& V <br>

\hline $\mathrm{f}_{\text {Clkout }}$ \& Output Clock Frequency Range \& 0 \& \& 3.0 \& GHz <br>
\hline $\mathrm{t}_{\mathrm{pd}}$ \& Propagation Delay CLKx to Qx (Differential Configuration) \& 360 \& 485 \& 610 \& ps <br>

\hline $\mathrm{t}_{\text {skew }}$ \& | Within Device Output-to-Output Skew (Differential Configuration) Device-to-Device Skew |
| :--- |
| Output Pulse Skew (Duty Cycle Skew) (Note 8) | \& \& \[

$$
\begin{aligned}
& 25 \\
& 30 \\
& 10
\end{aligned}
$$

\] \& \[

$$
\begin{gathered}
50 \\
250 \\
60
\end{gathered}
$$
\] \& ps <br>

\hline DCO \&  \& $$
\begin{aligned}
& 49.4 \\
& 45.2
\end{aligned}
$$ \& \& \[

$$
\begin{aligned}
& 50.6 \\
& 54.8
\end{aligned}
$$
\] \& \% <br>

\hline $\mathrm{t}_{\text {IIT }}$ \& CLOCK Random Jitter (RMS) (SELO $\neq$ SEL1) (Note 10) \& \& 0.3 \& 0.8 \& ps <br>
\hline $\mathrm{tr}_{\mathrm{r}}, \mathrm{t}_{\mathrm{f}}$ \& Output Rise/Fall Times (Note 11) CLKx / CLKx \& 50 \& 130 \& 300 \& ps <br>
\hline tpdL \& Output Disable Time, T = CLK period \& $2.5 \mathrm{~T}+\mathrm{tPD}$ \& \& $3.5 \mathrm{~T}+\mathrm{tPD}$ \& ns <br>
\hline tPLD \& Output Enable Time, T = CLK period \& $3 \mathrm{~T}+\mathrm{t}_{\text {PD }}$ \& \& $4 \mathrm{~T}+\mathrm{t}_{\text {PD }}$ \& ns <br>
\hline
\end{tabular}

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.
6. LVPECL Outputs loaded with $50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2.0 \mathrm{~V}$.
7. $\mathrm{V}_{\text {OUtPp }} \mathrm{MIN}=0.1 \mathrm{~V} @+85^{\circ} \mathrm{C}, \mathrm{f}_{\mathrm{O}}<3.0 \mathrm{GHz}$.
8. Output Pulse Skew is the absolute difference of the propagation delay times: $\left|\mathrm{t}_{\mathrm{PLH}}-\mathrm{t}_{\text {PHL }}\right|$
9. $\mathrm{DCO}_{\text {MIN } / \mathrm{MAX}}=43.2 \% / 59.2 \%$ @ $+85^{\circ} \mathrm{C}$.
10. $\mathrm{t}_{\mathrm{ITM}}$ MAX $=1.6 \mathrm{ps} @ 85^{\circ} \mathrm{C}, 3.0 \mathrm{~V}$
11. Measured $20 \%$ to $80 \%$.


Figure 3. Output Disable / Enable Timing


Figure 4. Output Voltage Amplitude (VOUTPP) versus Clock Output Frequency at Ambient Temperature (Typical)


Figure 5. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D - Termination of ECL Logic Devices.)

## Example Configurations



Figure 6. $2 \times 2$ Clock Switch

| SEL0 | SEL1 | Switch Configuration |
| :---: | :---: | :--- |
| 0 | 0 | CLK0 Clocks System A and <br> System B |
| 0 | 1 | CLK1 Clocks System A and <br> System B |
| 1 | 0 | CLK0 Clocks System A and CLK1 <br> Clocks System B |
| 1 | 1 | CLK1 Clocks System B and CLK1 <br> Clocks System A |



Figure 7. 1:6 Clock Fanout Buffer


Figure 8. Loopback Device

| SEL0 | SEL1 | Switch Configuration |
| :---: | :---: | :--- |
| 0 | 0 | System Loopback |
| 0 | 1 | Line Loopback |
| 1 | 0 | Transmit/Receive Operation |
| 1 | 1 | System and Line Loopback |

## APPLICATIONS INFORMATION

## Maintaining Lowest Device Skew

The NB4L6254 guarantees low output-output bank skew at 50 ps and a part-to-part skew of 250 ps . To ensure low skew clock signals in the application, both outputs of any differential output pair need to be terminated identically, even if only one output is used. When fewer than all nine output pairs are used, identical termination of all output pairs within the output bank is recommended. If an entire output bank is not used, it is recommended to leave all of these outputs open and unterminated. This will reduce the device power consumption while maintaining minimum output skew.

## Power Supply Bypassing

The NB4L6254 is a mixed analog/digital product. The differential architecture of the NB4L6254 supports low noise signal operation at high frequencies. In order to maintain its superior signal quality all $\mathrm{V}_{\mathrm{CC}}$ pins should be bypassed by high-frequency ceramic capacitors connected to GND. If the spectral frequencies of the internally generated switching noise on the supply pins cross the series resonant port of an individual bypass capacitor, its overall impedance begins to look inductive and thus increases with increasing frequency. The parallel capacitor combination shown ensures that a low impedance path to ground exists for frequencies well above the noise bandwidth.


Figure 9. $\mathbf{V}_{\mathrm{CC}}$ Power Supply Bypass

ORDERING INFORMATION

| Device | Package | Shipping $^{\dagger}$ |
| :---: | :---: | :---: |
| NB4L6254FAR2G | LQFP-32 <br> (Pb-Free) | $2000 /$ Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

LQFP-32, 7x7
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[^0]:    ## ORDERING INFORMATION

    See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

